

2N4403
Rev.F Sep.-2016

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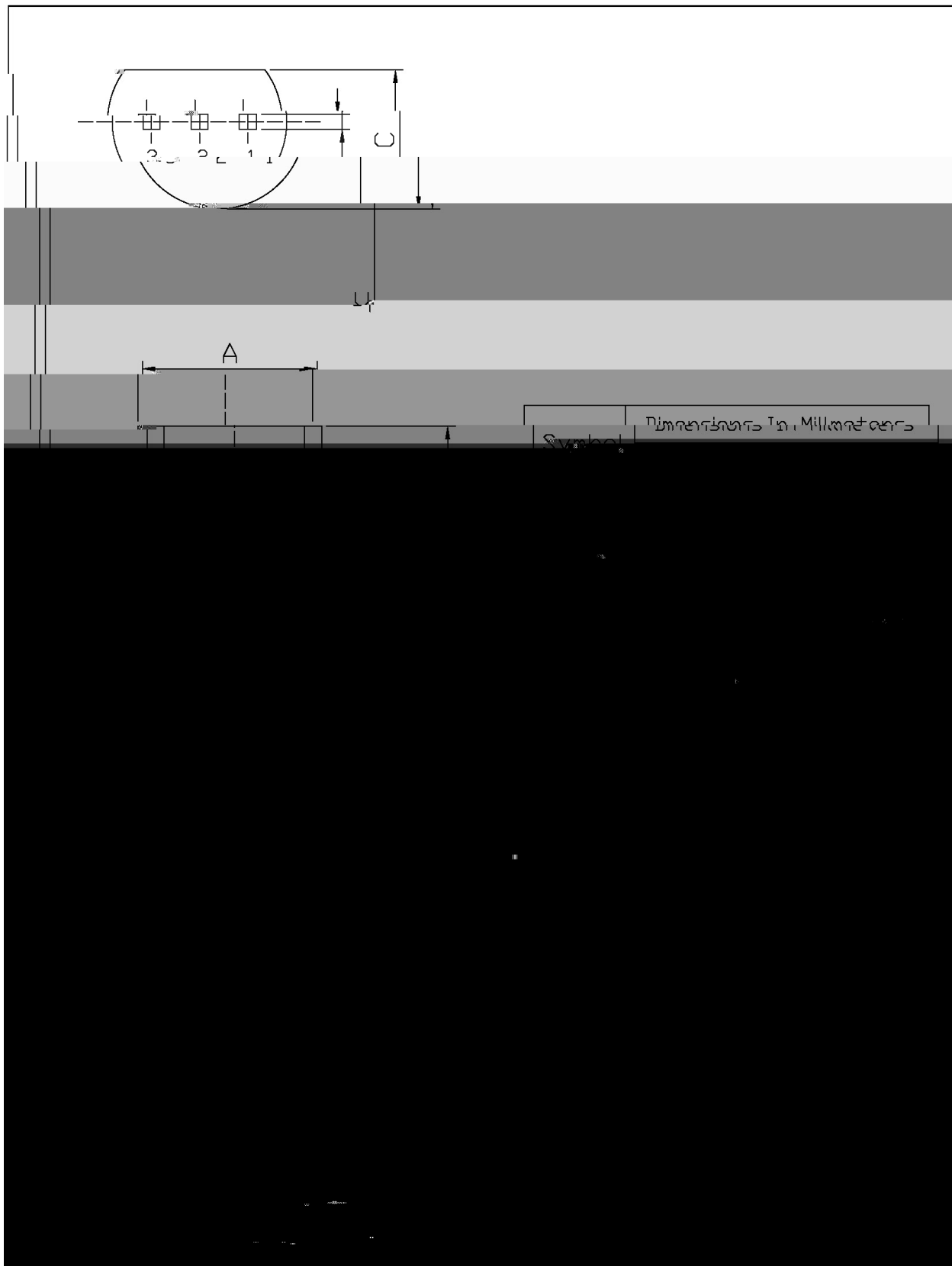
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-40	V
Collector to Emitter Voltage	V_{CEO}	-40	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-600	mA
Collector Power Dissipation	P_C	625	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	200	/W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C = -0.1mA$ $I_E = 0$	-40			V
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C = -1.0mA$ $I_B = 0$	-40			V
Emitter to Base Breakdown Voltage	V_{EBO}	$I_E = -0.1mA$ $I_C = 0$	-5.0			V
Collector Cut-Off Current	I_{CBO}	$V_{CB} = -40V$ $I_E = 0$			-50	nA

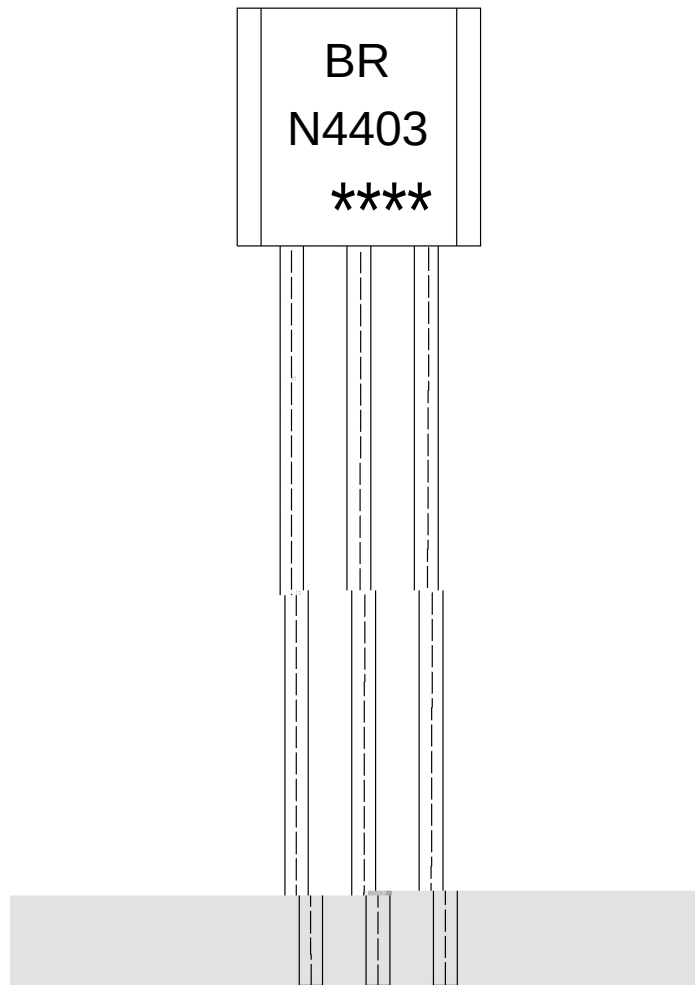
/ Package Dimensions

TO-92

Unit: mm



/ Marking Instructions



Б " X

EU X

Q7736 X

---- X

Note:

BR:

N4403:

****:

Б 3 " П

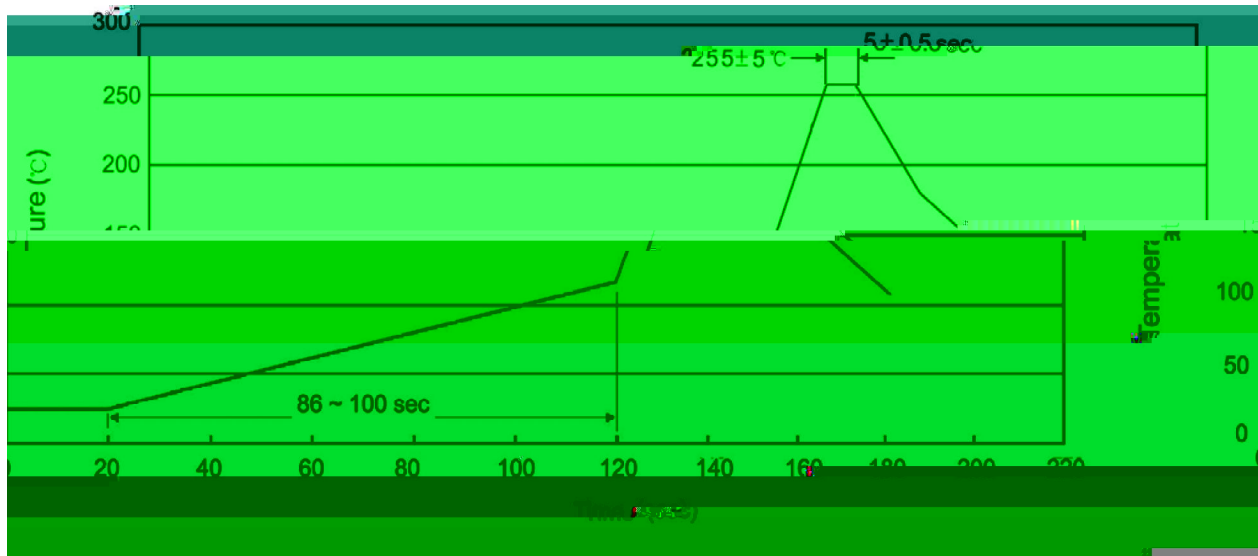
Б 3 " П

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Company Code.

Product Type.

Lot No. Code, code change with Lot No.


() / Temperature Profile for Dip Soldering(Pb-Free)


说明

1. 预加热: 25~150℃, 时间: 60~90sec;
2. 峰值温度: 255±5℃, 持续时间: 5±0.5sec;
3. 冷却速度: 2~10℃/sec.

Note:

1. Preheating: 25~150℃, Time: 60~90sec.
2. Peak Temp.: 255±5℃, Duration: 5±0.5sec.
3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

预加热: 270±5℃

时间: 10±1 sec.

$T_f = 0.56 \Delta T_b \sqrt{t} / T T_2$

1

$T_f = 2$

0

$TD = 0.0005$;